

Vishay Siliconix

# N-Channel 60 V (D-S) MOSFET



#### Marking code: G3

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	60				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$	0.144				
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.200				
Q <sub>g</sub> typ. (nC)	1.05				
I <sub>D</sub> (A) <sup>d</sup>	2.6				
Configuration	Single				

#### **FEATURES**

- TrenchFET® Gen IV power MOSFET
- 100 % R<sub>g</sub> tested

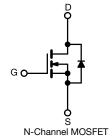




ROHS COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

- · Battery switch
- DC/DC converter
- · Load switch



ORDERING INFORMATION				
Package	SOT-23			
Lead (Pb)-free and halogen-free	Si2308CDS-T1-GE3			

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V <sub>DS</sub>	60	V
Gate-source voltage		V <sub>GS</sub>	± 20	V
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C		2.6	
	T <sub>C</sub> = 70 °C		2.1	
	T <sub>A</sub> = 25 °C	I <sub>D</sub>	1.9 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		1.5 <sup>a, b</sup>	
Pulsed drain current (t = 100 μs)		I <sub>DM</sub>	6	Α
Continuous source-drain diode current	T <sub>C</sub> = 25 °C		1.3	
	T <sub>A</sub> = 25 °C	I <sub>S</sub>	0.72 <sup>a, b</sup>	
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	4	
Single pulse avalanche energy	L = U. I IIII	E <sub>AS</sub>	0.8	mJ
Maximum power dissipation	T <sub>C</sub> = 25 °C		1.6	
	T <sub>C</sub> = 70 °C		1	10/
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.9 <sup>a, b</sup>	W
	T <sub>A</sub> = 70 °C		0.6 <sup>a, b</sup>	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stq</sub>	-55 to +150	°C

THERMAL RESISTANCE RATINGS							
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT			
Maximum junction-to-ambient a, c	t ≤ 10 s	R <sub>thJA</sub>	120	145	°C/W		
Maximum junction-to-foot (drain)	Steady state	$R_{thJF}$	62	78	C/VV		

#### Notes

- a. Surface mounted on 1" x 1" FR4 board
- b. t = 10 s
- c. Maximum under steady state conditions is 175 °C/W
- d.  $T_C = 25$  °C

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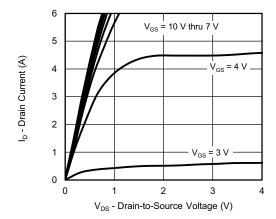
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	40	-	mV/°C	
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-4.5	-		
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1	-	3	V	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
Zero gate voltage drain current	I <sub>DSS</sub> -	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V		-	1		
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C	-	-	10	μA	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le 10 \text{ V}, V_{GS} = 10 \text{ V}$	6	-	-	Α	
Duning and a state was interest 2	Б	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.9 A	-	0.120	0.144	Ω	
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 1.5 \text{ A}$	-	0.160	0.200		
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 30 \text{ V}, I_{D} = 1.9 \text{ A}$	-	3.2	-	S	
Dynamic <sup>b</sup>				•	•		
Input capacitance	C <sub>iss</sub>		-	105	-	pF	
Output capacitance	C <sub>oss</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	55	-		
Reverse transfer capacitance	C <sub>rss</sub>		-	7	-		
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.9 A	-	2	4	nC	
			1	1.05	2.1		
Gate-source charge	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 1.9 \text{ A}$	-	0.62	-		
Gate-drain charge	Q <sub>gd</sub>		-	0.17	-		
Gate resistance	$R_g$	f = 1 MHz	0.3	1.5	3	Ω	
Turn-on delay time	t <sub>d(on)</sub>		-	8	16		
Rise time	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, \text{ R}_L = 20 \Omega, \text{ I}_D \cong 1.5 \text{ A},$	-	5	10	]	
Turn-off delay time	t <sub>d(off)</sub>	$V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$	1	11	20		
Fall time	t <sub>f</sub>		-	3	6		
Turn-on delay time	t <sub>d(on)</sub>		-	23	35	ns	
Rise time	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, \text{ R}_L = 20 \Omega, \text{ I}_D \cong 1.5 \text{ A},$	-	25	40	- - -	
Turn-off delay time	t <sub>d(off)</sub>	$V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	10	20		
Fall time	t <sub>f</sub>		-	16	30		
Drain-Source Body Diode Characterist	cs						
Continuous source-drain diode current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	1.7	_	
Pulse diode forward current	I <sub>SM</sub>		-	-	4	A	
Body diode voltage	$V_{SD}$	I <sub>S</sub> = 1.5 A, V <sub>GS</sub> = 0 V	-	0.85	1.2	V	
Body diode reverse recovery time	t <sub>rr</sub>		-	15	30	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>	1 4 5 A 31/31 400 A/ T 05 30	-	53	80	nC	
Reverse recovery fall time	t <sub>a</sub>	$I_F = 1.5 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	-	27	-		
Reverse recovery rise time	t <sub>b</sub>		-	17	_	ns	

#### **Notes**

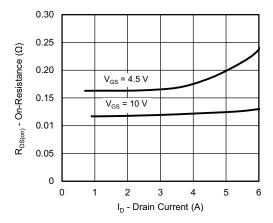
- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

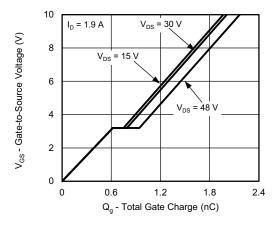




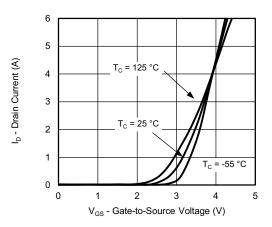
#### **Output Characteristics**



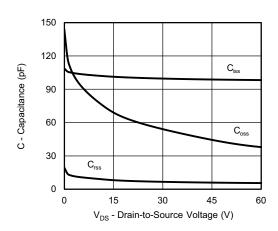
On-Resistance vs. Drain Current and Gate Voltage



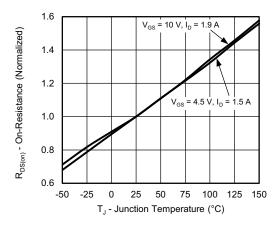
**Gate Charge** 



**Transfer Characteristics** 

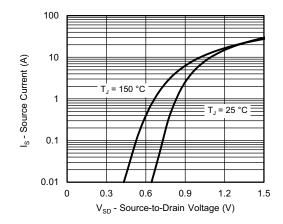


Capacitance

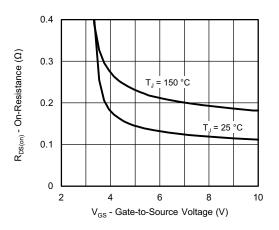


On-Resistance vs. Junction Temperature

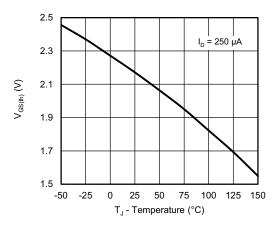




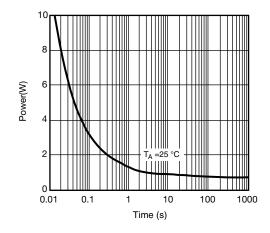
Source-Drain Diode Forward Voltage



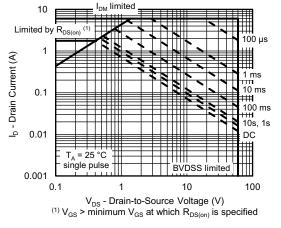
On-Resistance vs. Gate-to-Source Voltage



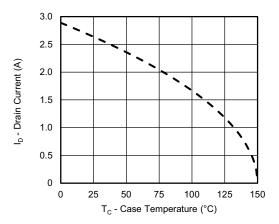
**Threshold Voltage** 



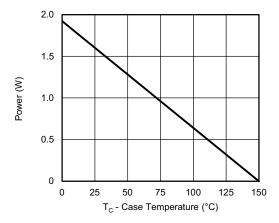
Single Pulse Power, Junction-to-Ambient

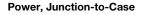


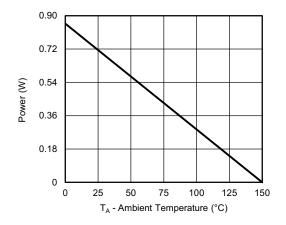
Safe Operating Area, Junction-to-Ambient



### Current Derating a



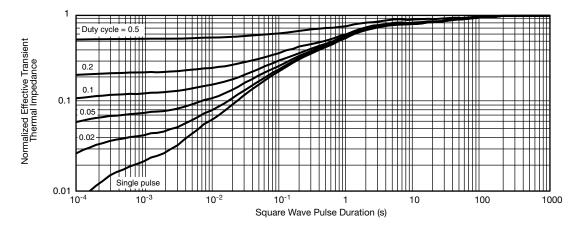




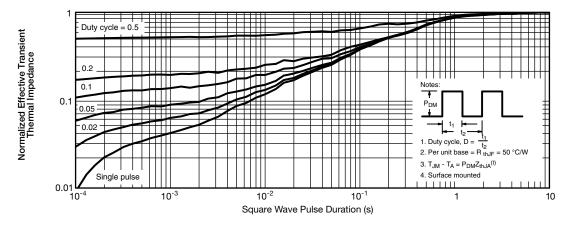
Power, Junction-to-Ambient

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?77744">www.vishay.com/ppg?77744</a>.

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# SOT-23 (TO-236): 3-LEAD







Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e <sub>1</sub>	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	lul-01	•			

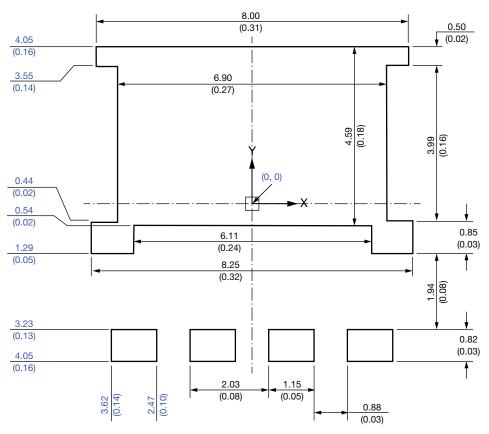
ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479

Document Number: 71196 www.vishay.com 09-Jul-01



# Recommended Minimum PADs for PowerPAK® 8 x 8L Single



#### Dimensions in millimeters (inches)

#### Note

• Linear dimensions are in black, the same information is provided in ordinate dimensions which are in blue.



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